



DEFENSE LOGISTICS AGENCY
 LAND AND MARITIME
 POST OFFICE BOX 3990
 COLUMBUS OH 43218-3990

May 26, 2011

Ms. Renée Akers
 Lockheed Martin Mission Systems & Sensors
 1801 State Route 17C
 Owego, NY 13827

Dear Ms. Akers:

RE: Notification of Add –On Qualification, FSC 5998, MIL-PRF-31032, MIL-PRF-55110, CAGE Code: 03640, VQ (VQE-11-22596)

Add-on qualification of your product is granted under the current issue of the listed specifications as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1. This qualification is based on your technical review board (TRB) review and approval of the material and classification indicated below. Additionally, Lockheed Martin Mission Systems & Sensors, retains your cross listing to QPL-55110, per paragraph 6.3.4 of MIL-PRF-31032 and MIL-PRF-55110 appendix B. The effective date of this qualification is May 26, 2011. The items that changed in your qualification listing are highlighted.

MANUFACTURER NAME & ADDRESS	BASIC PLANT LOCATION	CAGE CODE: 03640
Lockheed Martin Mission Systems & Sensors 1801 State Route 17C Owego, NY 13827 US	SAME	PHONE: 607-751-4665 Fax : 607-751-7714 EMAIL: melita.nagerl@lmco.com
Specifications:	MIL-PRF-31032/1, MIL-PRF-31032/2	
Qualification Letters:	VQE-00-0961, VQE-07-013268, VQE-07-013459, VQE-99-0130, VQE-11-022596	
Rigid Base Materials:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant	
Max. Panel Size:	24" X 30"	
Max. Number of Layers:	24	
Max Board Thickness:	0.2"	
Min. Hole Size:	0.018" Drilled Plated-Through Hole Before Plating	
Aspect Ratio:	8:1 Through-Hole	
Min. Conductor Width/Space:	0.004"/0.004"	
Hole Preparation:	Permanganate Desmear, Plasma Etchback	
Hole Wall Conductive Coating	Electroless Copper	
Copper Plating:	Direct Current Plate	
Solder Resist:	Liquid Photoimageable, Dry Film	
Finish Systems:	HASL, Electrolytic Ni /Hard Au, Hot Oil Reflow of Plated Sn/Pb	

This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this office immediately if a failure occurs during Periodic Conformance Inspection (PCI) or Capability Verification Inspection (CVI) testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML/QPL products.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Bill Werman at bill.werman@dla.mil or at (614) 692-0631.

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE
Chief
Sourcing and Qualifications Division